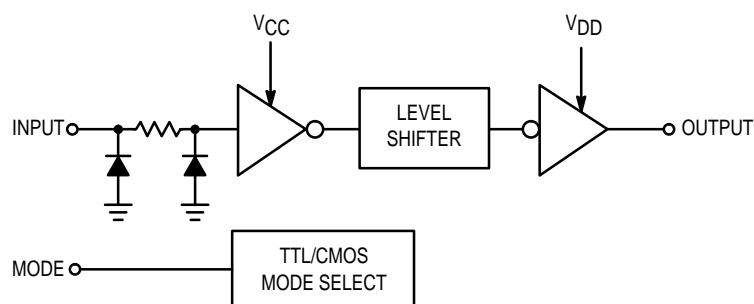


## Hex Level Shifter for TTL to CMOS or CMOS to CMOS

The MC14504B is a hex non-inverting level shifter using CMOS technology. The level shifter will shift a TTL signal to CMOS logic levels for any CMOS supply voltage between 5 and 15 volts. A control input also allows interface from CMOS to CMOS at one logic level to another logic level: Either up or down level translating is accomplished by selection of power supply levels  $V_{DD}$  and  $V_{CC}$ . The  $V_{CC}$  level sets the input signal levels while  $V_{DD}$  selects the output voltage levels.

- UP Translates from a Low to a High Voltage or DOWN Translates from a High to a Low Voltage
- Input Threshold Can Be Shifted for TTL Compatibility
- No Sequencing Required on Power Supplies or Inputs for Power Up or Power Down
- 3 to 18 Vdc Operation for  $V_{DD}$  and  $V_{CC}$
- Diode Protected Inputs to  $V_{SS}$
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky TTL Load Over the Rated Temperature Range

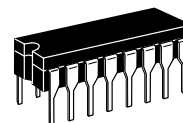
### LOGIC DIAGRAM



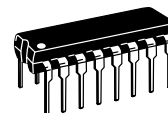
Mode Select	Input Logic Levels	Output Logic Levels
1 ( $V_{CC}$ )	TTL	CMOS
0 ( $V_{SS}$ )	CMOS	CMOS

1/6 of package shown.

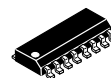
## MC14504B



**L SUFFIX**  
CERAMIC  
CASE 620



**P SUFFIX**  
PLASTIC  
CASE 648



**D SUFFIX**  
SOIC  
CASE 751B

### ORDERING INFORMATION

MC14XXXBCP Plastic  
MC14XXXBCL Ceramic  
MC14XXXBD SOIC

$T_A = -55^\circ$  to  $125^\circ\text{C}$  for all packages.

### PIN ASSIGNMENT

$V_{CC}$	1	16	$V_{DD}$
$A_{out}$	2	15	$F_{out}$
$A_{in}$	3	14	$F_{in}$
$B_{out}$	4	13	MODE
$B_{in}$	5	12	$E_{out}$
$C_{out}$	6	11	$E_{in}$
$C_{in}$	7	10	$D_{out}$
$V_{SS}$	8	9	$D_{in}$

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields referenced to the  $V_{SS}$  pin, only. Extra precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, the ranges  $V_{SS} \leq V_{in} \leq 18\text{ V}$  and  $V_{SS} \leq V_{out} \leq V_{DD}$  are recommended.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.

**MAXIMUM RATINGS\*** (Voltages Referenced to V<sub>SS</sub>)

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	– 0.5 to 18.0	V
V <sub>DD</sub>	DC Supply Voltage	– 0.5 to + 18.0	V
V <sub>in</sub>	Input Voltage (DC or Transient)	– 0.5 to + 18.0	V
V <sub>out</sub>	Output Voltage (DC or Transient)	– 0.5 to V <sub>DD</sub> + 0.5	V
I <sub>in</sub> , I <sub>out</sub>	Input or output Current (DC or Transient), per Pin	± 10	mA
P <sub>D</sub>	Power Dissipation, per Package*	500	mW
T <sub>stg</sub>	Storage Temperature	– 65 to + 150	°C
T <sub>L</sub>	Lead Temperature (8–Second Soldering)	260	°C

\* Maximum Ratings are those values beyond which damage to the device may occur.

† Temperature Derating:

Plastic “P and D/DW” Packages: – 7.0 mW/°C From 65°C To 125°C

Ceramic “L” Packages: – 12 mW/°C From 100°C To 125°C

**ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

Characteristic	Symbol	V <sub>CC</sub> Vdc	V <sub>DD</sub> Vdc	– 55°C		25°C			125°C		Unit
				Min	Max	Min	Typ #	Max	Min	Max	
Output Voltage V <sub>in</sub> = 0 V  V <sub>in</sub> = V <sub>CC</sub>	V <sub>OL</sub>	—	5.0	—	0.05	—	0	0.05	—	0.05	Vdc
		—	10	—	0.05	—	0	0.05	—	0.05	
		—	15	—	0.05	—	0	0.05	—	0.05	
	V <sub>OH</sub>	—	5.0	4.95	—	4.95	5.0	—	4.95	—	Vdc
		—	10	9.95	—	9.95	10	—	9.95	—	
		—	15	14.95	—	14.95	15	—	14.95	—	
Input Voltage “0” Level (V <sub>OL</sub> = 1.0 Vdc) TTL–CMOS (V <sub>OL</sub> = 1.5 Vdc) TTL–CMOS (V <sub>OL</sub> = 1.0 Vdc) CMOS–CMOS (V <sub>OL</sub> = 1.5 Vdc) CMOS–CMOS (V <sub>OL</sub> = 1.5 Vdc) CMOS–CMOS	V <sub>IL</sub>	5.0	10	—	0.8	—	1.3	0.8	—	0.8	Vdc
		5.0	15	—	0.8	—	1.3	0.8	—	0.8	
		5.0	10	—	1.5	—	2.25	1.5	—	1.4	
		5.0	15	—	1.5	—	2.25	1.5	—	1.5	
		10	15	—	3.0	—	4.5	3.0	—	2.9	
		—	—	—	—	—	—	—	—	—	
Input Voltage “1” Level (V <sub>OH</sub> = 9.0 Vdc) TTL–CMOS (V <sub>OH</sub> = 13.5 Vdc) TTL–CMOS (V <sub>OH</sub> = 9.0 Vdc) CMOS–CMOS (V <sub>OH</sub> = 13.5 Vdc) CMOS–CMOS (V <sub>OH</sub> = 13.5 Vdc) CMOS–CMOS	V <sub>IH</sub>	5.0	10	2.0	—	2.0	1.5	—	2.0	—	Vdc
		5.0	15	2.0	—	2.0	1.5	—	2.0	—	
		5.0	10	3.6	—	3.5	2.75	—	3.5	—	
		5.0	15	3.6	—	3.5	2.75	—	3.5	—	
		10	15	7.1	—	7.0	5.5	—	7.0	—	
		—	—	—	—	—	—	—	—	—	
Output Drive Current (V <sub>OH</sub> = 2.5 Vdc) (V <sub>OH</sub> = 4.6 Vdc) (V <sub>OH</sub> = 9.5 Vdc) (V <sub>OH</sub> = 13.5 Vdc)  (V <sub>OL</sub> = 0.4 Vdc) (V <sub>OL</sub> = 0.5 Vdc) (V <sub>OL</sub> = 1.5 Vdc)	Source I <sub>OH</sub>	—	5.0	– 3.0	—	– 2.4	– 4.2	—	– 1.7	—	mAdc
		—	5.0	– 0.64	—	– 0.51	– 0.88	—	– 0.36	—	
		—	10	– 1.6	—	– 1.3	– 2.25	—	– 0.9	—	
		—	15	– 4.2	—	– 3.4	– 8.8	—	– 2.4	—	
	Sink I <sub>OL</sub>	—	5.0	0.64	—	0.51	0.88	—	0.36	—	mAdc
		—	10	1.6	—	1.3	2.25	—	0.9	—	
Input Current	I <sub>in</sub>	—	15	—	± 0.1	—	± 0.00001	± 0.1	—	± 1.0	μAdc
		—	—	—	—	—	5.0	7.5	—	—	
		—	—	—	—	—	—	—	—	—	
Input Capacitance (V <sub>in</sub> = 0)	C <sub>in</sub>	—	—	—	—	—	5.0	7.5	—	—	pF
		—	—	—	—	—	—	—	—	—	
		—	—	—	—	—	—	—	—	—	
Quiescent Current (Per Package) CMOS–CMOS Mode	I <sub>DD</sub> or I <sub>CC</sub>	—	5.0	—	0.05	—	0.0005	0.05	—	1.5	μAdc
		—	10	—	0.10	—	0.0010	0.10	—	3.0	
		—	15	—	0.20	—	0.0015	0.20	—	6.0	
Quiescent Current (Per Package) TTL–CMOS Mode	I <sub>DD</sub>	5.0	5.0	—	0.5	—	0.0005	0.5	—	3.8	μAdc
		5.0	10	—	1.0	—	0.0010	1.0	—	7.5	
		5.0	15	—	2.0	—	0.0015	2.0	—	15	
Quiescent Current (Per Package) TTL–CMOS Mode	I <sub>CC</sub>	5.0	5.0	—	5.0	—	2.5	5.0	—	6.0	mAdc
		5.0	10	—	5.0	—	2.5	5.0	—	6.0	
		5.0	15	—	5.0	—	2.5	5.0	—	6.0	

#Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.

SWITCHING CHARACTERISTICS (C<sub>L</sub> = 50 pF, T<sub>A</sub> = 25°C)

Characteristic	Symbol	Shifting Mode	V <sub>CC</sub> Vdc	V <sub>DD</sub> Vdc	Limits			Unit
					Min	Typ #	Max	
Propagation Delay, High to Low	t <sub>PHL</sub>	TTL – CMOS V <sub>DD</sub> > V <sub>CC</sub>	5.0	10	—	140	280	ns
			5.0	15	—	140	280	
			10	15	—	70	140	
		CMOS – CMOS V <sub>DD</sub> > V <sub>CC</sub>	5.0	10	—	120	240	
			5.0	15	—	120	240	
			10	15	—	70	140	
Propagation Delay, Low to High	t <sub>PLH</sub>	TTL – CMOS V <sub>DD</sub> > V <sub>CC</sub>	5.0	10	—	170	340	ns
			5.0	15	—	160	320	
			10	15	—	100	200	
		CMOS – CMOS V <sub>DD</sub> > V <sub>CC</sub>	5.0	10	—	170	340	
			5.0	15	—	170	340	
			10	15	—	100	200	
Output Rise and Fall Time	t <sub>TLH</sub> , t <sub>THL</sub>	ALL	—	5.0	—	100	200	ns
			—	10	—	50	100	
			—	15	—	40	80	

#Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.

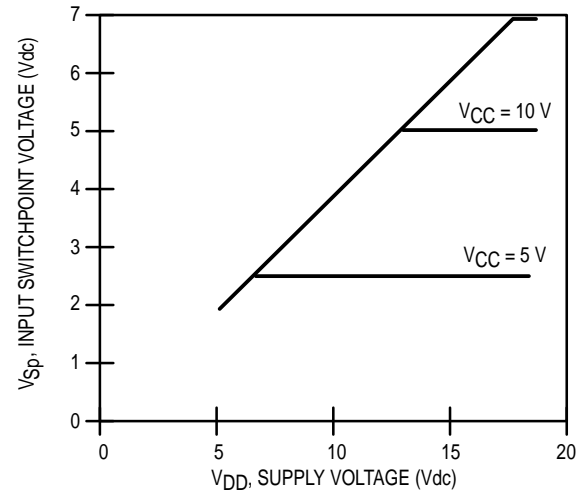


Figure 1. Input Switchpoint CMOS to CMOS Mode

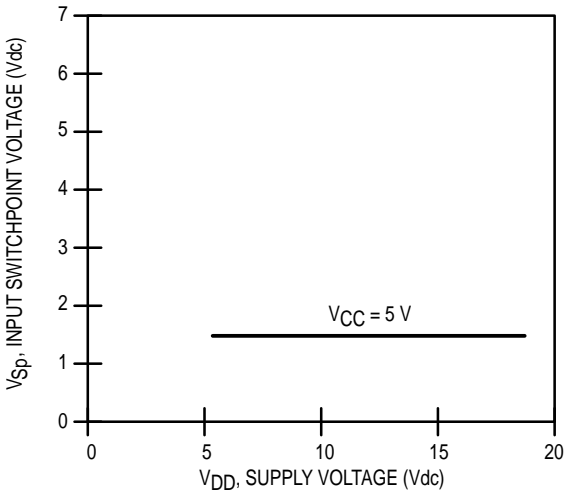


Figure 2. Input Switchpoint TTL to CMOS Mode

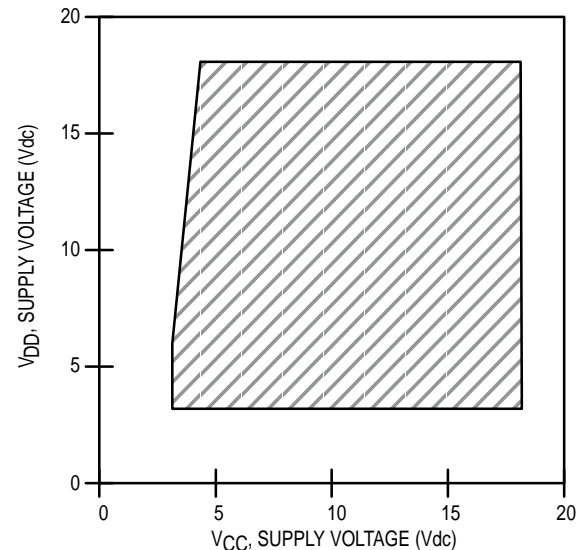


Figure 3. Operating Boundary CMOS to CMOS Mode

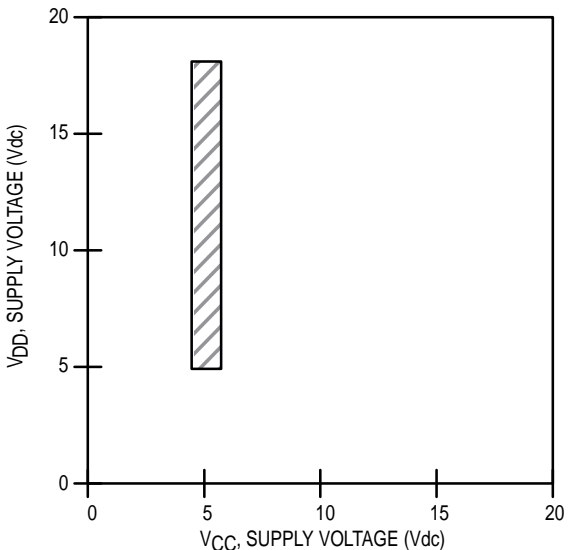
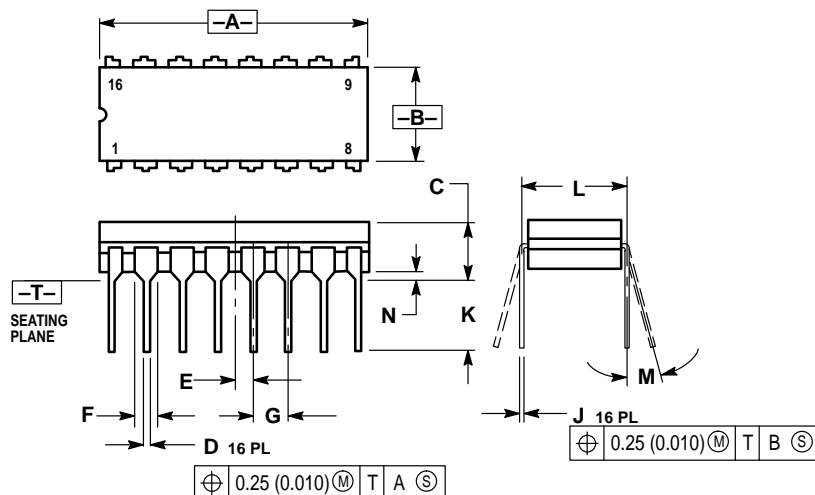


Figure 4. Operating Boundary TTL to CMOS Mode

## OUTLINE DIMENSIONS

### L SUFFIX CERAMIC DIP PACKAGE CASE 620-10 ISSUE V

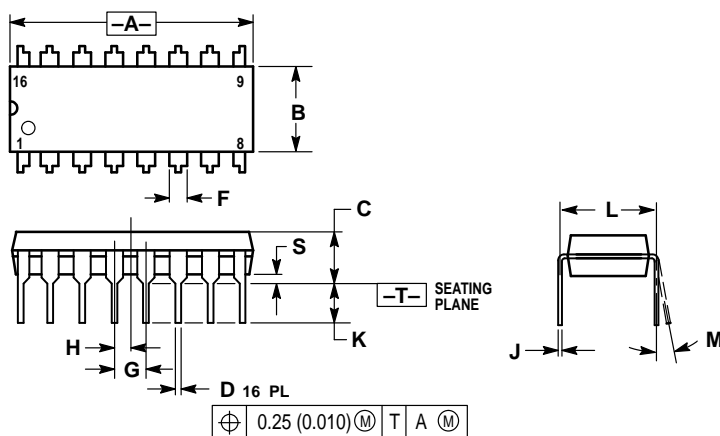


#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	—	0.200	—	5.08
D	0.015	0.020	0.39	0.50
E	0.050	BSC	1.27	BSC
F	0.055	0.065	1.40	1.65
G	0.100	BSC	2.54	BSC
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300	BSC	7.62	BSC
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

### P SUFFIX PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



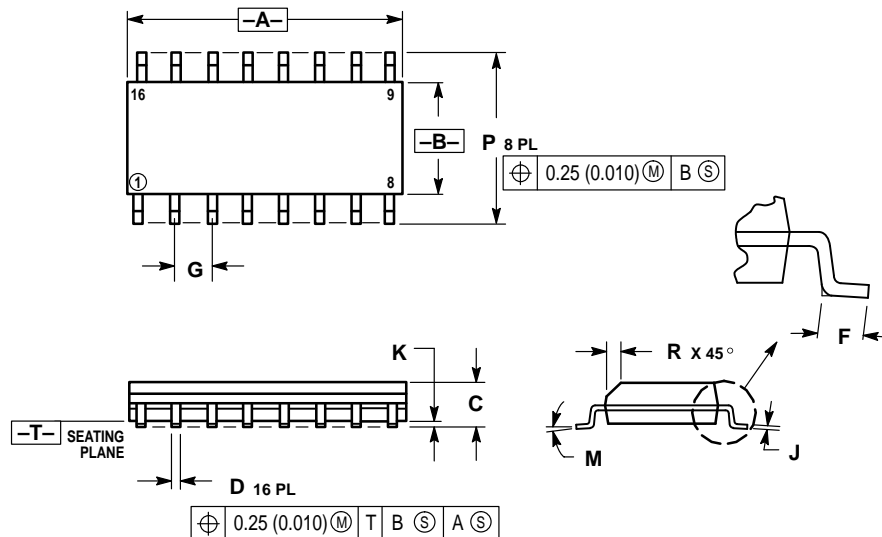
#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54	BSC
H	0.050	BSC	1.27	BSC
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

## OUTLINE DIMENSIONS


### D SUFFIX PLASTIC SOIC PACKAGE CASE 751B-05 ISSUE J



#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
E	0.40	1.25	0.016	0.049
F	1.27 BSC		0.050 BSC	
G	0.19	0.25	0.008	0.009
H	0.10	0.25	0.004	0.009
I	0°	7°	0°	7°
J	5.80	6.20	0.229	0.244
K	0.25	0.50	0.010	0.019

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MC14504B/D

